10061913-101CLF - PCI Express : Surface Mount Card Edge Connector, 64 Positions

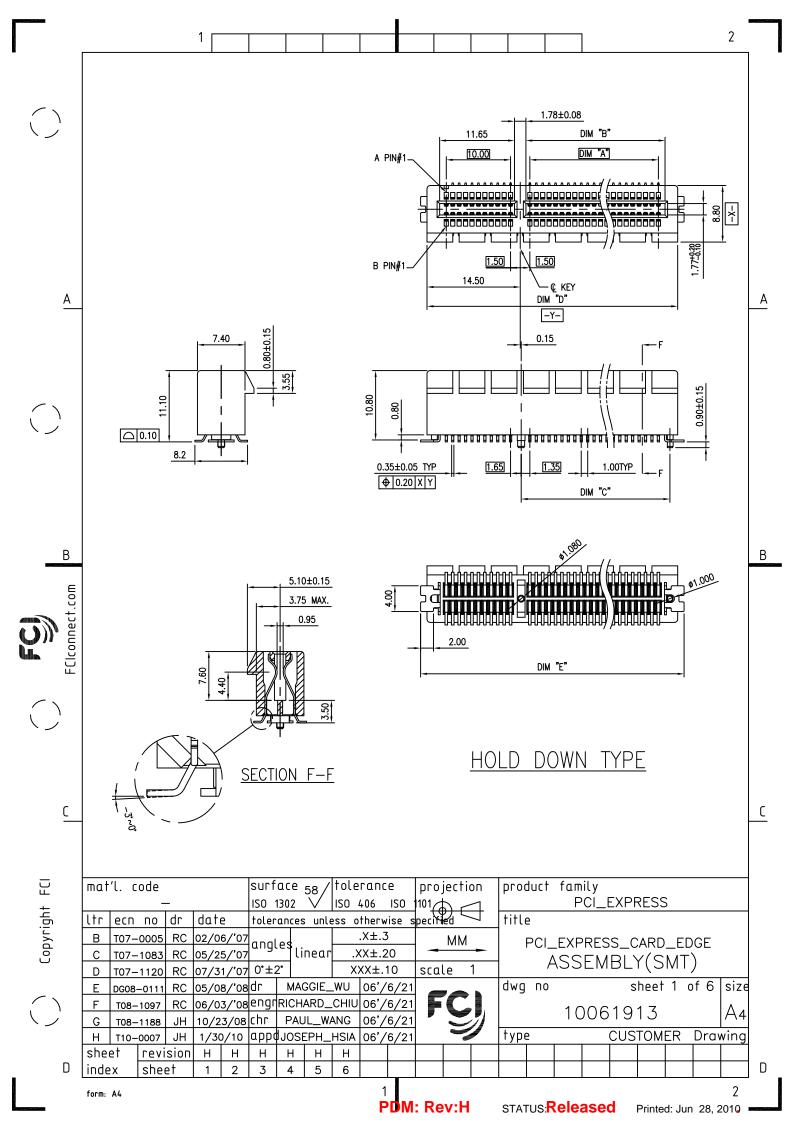


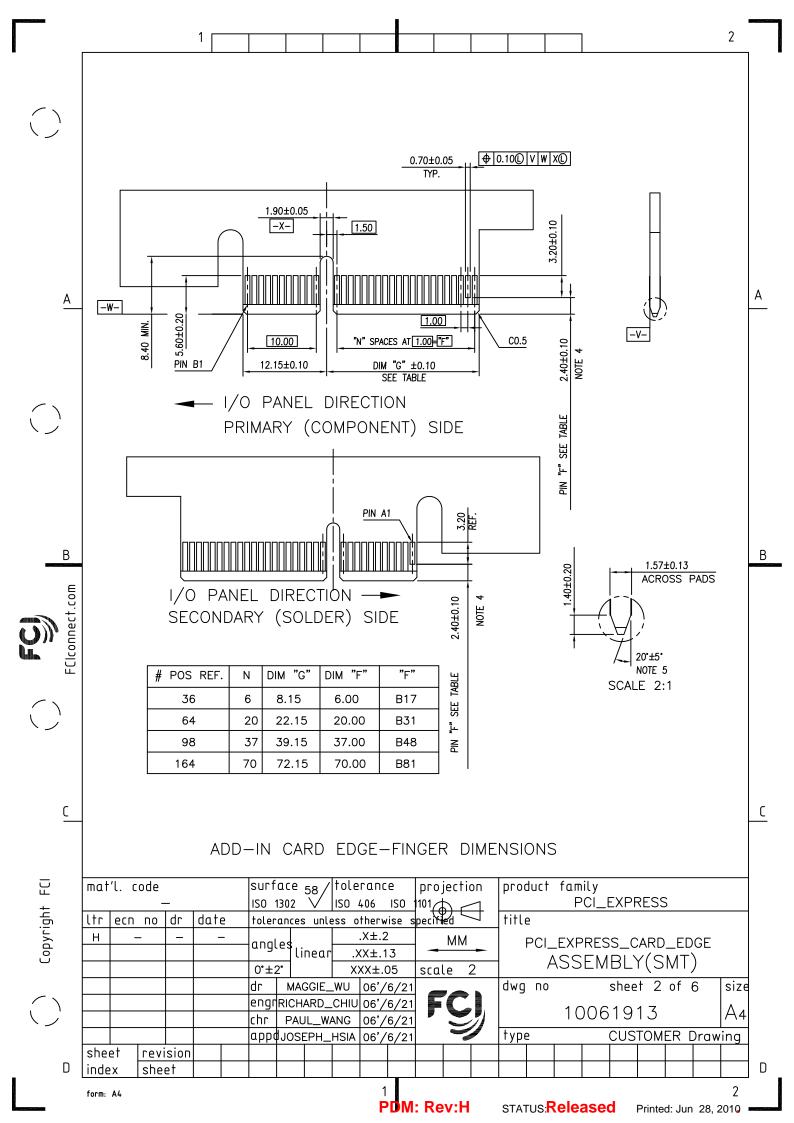


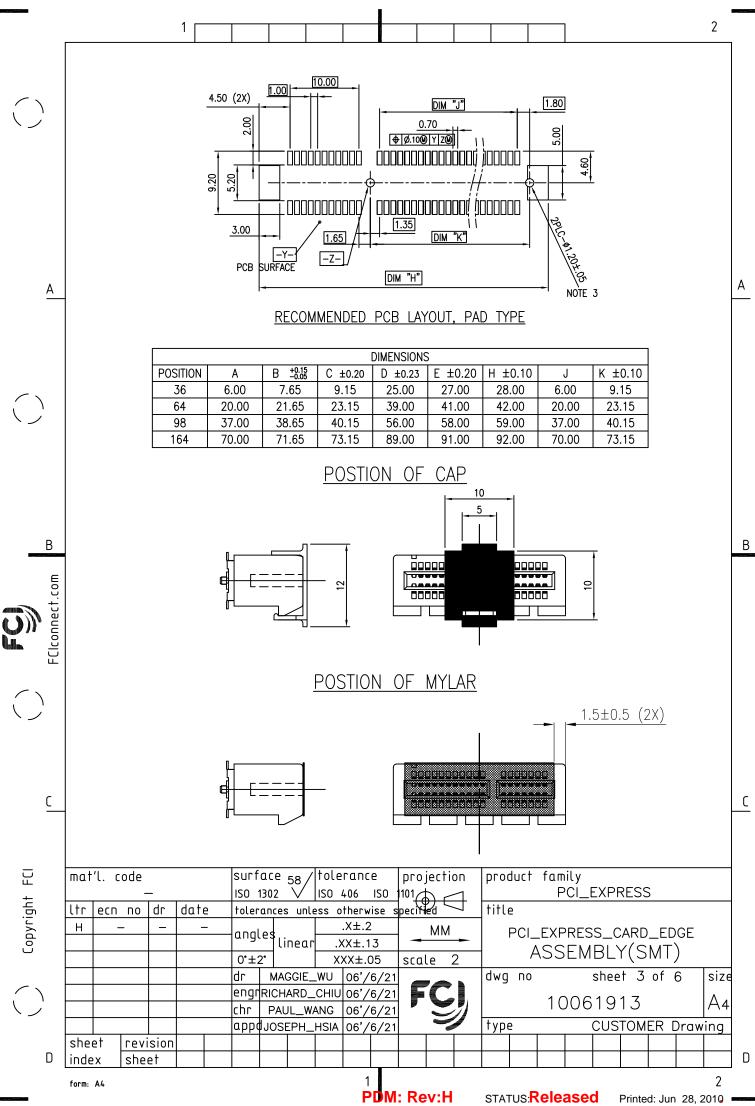
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Specifications

General	
Component Type	Surface Mount Connector
Number of contacts (Total)	64 (x4)
Orientation (Features)	Plastic Post
Dimensional	
Thickness (Board)	1.56 mm (0.062 in.)
PCB Thickness (Add-In)	1.57 mm (0.062 in.)
Electrical	
Current rating	1.1 amps per contact
Resistance (Contact)	30 milli ohms max. (Initial) with 10 milli ohms max. change after Exposure Testing
Resistance (Insulation)	1000 M-ohms
Voltage rating	300V AC
Mechanical	
Durability (Mating cycles)	50
Withdrawal Force	0.15N minmum per Contact pair
Mating force	1.15N maximum per Contact pair
Mounting	
Solder process	Reflow Solder
Physical	
Color (Housing)	Black
Material (Contact)	Copper Alloy
Material (Housing)	High - Temperature Nylon, Glass - Filled, UL94V-0
Plating (Contact area)	0.76 μm (30 μin.) Gold over 1.27 μm (50 μin.) Nickel
Plating (Solder area)	2.54 μm (100 μin.) Tin over 1.27 μm (50 μin.) Nickel
Temperature (Range)	-55°C to +85°C
Approvals / Certifications	
Approvals / Certifications	UL Approved
Other Features	
Packaging (Type)	Tray with Cap







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	NOTES: 1.MATERIAL: HOUSING: NYLON, GLASS FILLED UL94V-0 RATE, SUITABLE FOR I.R SOLDERING. TERMINAL: COPPER ALLOY	
<u>A</u>	 PLATING: 500" NICKEL UNDERPLATE ALL OVER CONTACT AREA PLATING - SEE PRODUCT NUMBER CODE SOLDER TAIL: TIN 1000" OVER 500" NICKEL METAL PADS: COPPER ALLOY FINISH: 1000" TIN OVER 500" NICKEL 2.PRODUCT SPECIFICATION: GS-12-390 (3)THE HORIZONTAL AXIS FOR THE PAD PATTERN IS ESTABLISHED BY A LINE THROUGH THE CENTER OF THE TWO Ø1.0 HOLES. THE VERTICAL AXIS IS 90' TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM -Z (4)NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1. (5)CHAMFER EDGES MUST BE FREE OF CUTTING BURRS. 	<u>A</u>
	 7.RoHS COMPATIBLE PRODUCT SPECIFICATIONS a – PLATING: a "LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um MINIMUM NICKEL UNDERPLATE. b – MANUFACTURING PROCESS COMPATIBILITY THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C PEAK TEMPERATURE FOR 5 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN. 	
В	PRODUCT NUMBER CODE 10061913-x x x x L F HOUSING COLOR OPTIONS	В
FClconnect.com	0WHITE 1-BLACK PACKAGING OPTIONS T-TRAY PACKAGING WITHOUT CAP R-TAPE & REEL PACKING WITHOUT CAP OR MYLAR (FOR 36P & 64P OPTION ONLY) P-TAPE & REEL PACKING WITH CAP (FOR 36P & 64P OPTION ONLY) C-TRAY PACKAGING WITH CAP M-TAPE & REEL PACKING WITH MYLAR (FOR 36P & 64P OPTION ONLY) N-TRAY PACKAGING WITH MAYLAR Y-HARD TRAY (FOR 164P ONLY) Z-HARD TRAY PACKAGING WITH MAYLAR (FOR 164P ONLY) Z-500" NI UNDERPLATE 0-36 JOOU" TIN TAIL AREA COMPATIBLE ROHS Z-500" NI UNDERPLATE 3-164 GOLD FLASH CONTACT AREA 100U" TIN	C
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